

Texas Instruments Inc.

WL1837MODCOM8I

WL1837MODGI COM8 Card

History Change

Revision	Date	Description	Prepared By
D01	2014/08/07	- Modified RF matching circuit and Net name. - Modified Assembling Item of PCM/BT_FUNC.	Hsinwei Wang
	2014/09/09	- Changed Project Code to GI - Updated RF matching.	
D02	2014/10/29	- Modified Net names.	Hsinwei Wang

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Title

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Document Number

WL1837MODCOM8I-SCH

Rev
D02

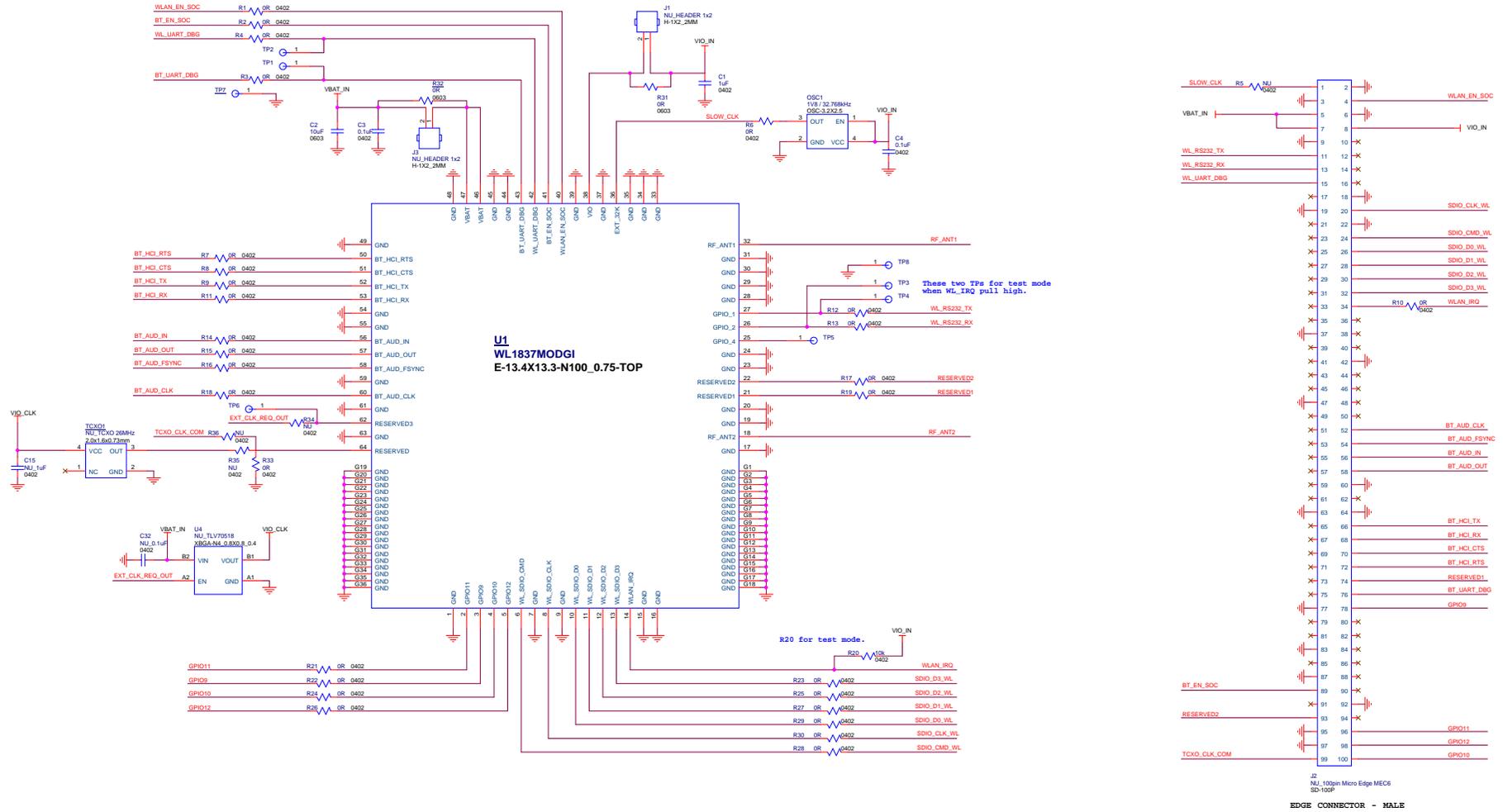
Date:

Wednesday, October 29, 2014

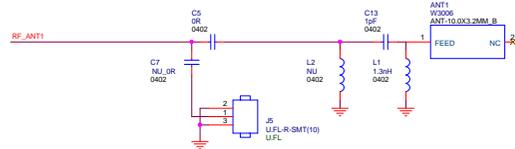
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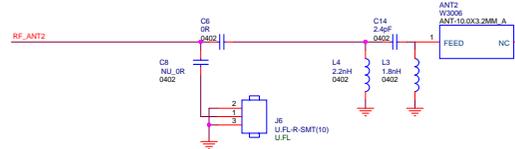
WL1837MODCOM8I Design



ANT1 - WL_2.4_IO2/BT/WL_5GHz



ANT2 - WL_2.4_IO1/WL_5GHz



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